IPC ASSOCIATION ELECTRONIC	Material Com © Copyright 2005. SINDUSTRIES international and P	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				Materials and	rials and Mfg Information			
uppliei	r Information													
Company name* Company				pany unique ID			Unique ID Authority				Response Date*			
nsemi											2024-05-02			
ontact N	ame	Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-I	Env-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorize	d Representative*	Title - Representative			P	Phone - Representative*			Emai	Email - Representative*				
Product-Env-Stewards Produ			Product Env	Product Enviro Compliance			NA			Prod	Product-Env-Stewards@onsemi.com			
	Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	Manufacturing S	Manufacturing Site		UOM	Unit Type	
		TIP32AG BIP T0220 PN		BIP T0220 PNP 3.	NP 3A 60V		2024-05-02		CN5	CN5		mg	Each	
lanufa	cturing Process Information		Terminal Base	Alloy	-STD-020 MS	I Patina	Dank Proce	es Rody Tamr	aratura May Tima s	at Pagk Tampe	aratura Numb	or of Poflow Cv	clas	
	8		CU Allov NA			L Kating	Peak Process Body Temperature Max Time a		1.	Peak Temperature Number of Reflow Cycles seconds 3				
omments	` /		Alloy	1	11.1				30	Sec	Jonus J			
Jimilents	1													
or more	information regarding materia	l composition	nlooso rofor t	n naga 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Iability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty right											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R		,									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55		Supplier	Silicon (Si)	7440-21-3		3.5145	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0355	mg
Die Attach	82.98	mg	A	Lead (Pb)	7439-92-1	7a	78.831	mg
			Supplier	Tin (Sn)	7440-31-5		4.149	mg
Lead Frame	1300.04	mg	Supplier	Copper (Cu)	7440-50-8		1300.04	mg
Mold Compound-Black	543.9			Brominated epoxy resin	proprietary data		10.878	mg
			Supplier	Phenolic Resin	Proprietary Data		27.195	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		16.317	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		435.12	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		54.39	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Al	0.41	mg	Supplier	Aluminum (Al)	7429-90-5		0.41	mg